

LME49860 44V Dual High Performance, High Fidelity Audio Operational Amplifier

Check for Samples: [LME49860](#), [LME49860MABD](#), [LME49860NABD](#)

FEATURES

- Easily drives 600Ω loads
- Optimized for superior audio signal fidelity
- Output short circuit protection
- PSRR and CMRR exceed 120dB (typ)
- SOIC, DIP packages

APPLICATIONS

- Ultra high quality audio amplification
- High fidelity preamplifiers
- High fidelity multimedia
- State of the art phono pre amps
- High performance professional audio
- High fidelity equalization and crossover networks
- High performance line drivers
- High performance line receivers
- High fidelity active filters

DESCRIPTION

The LME49860 is part of the ultra-low distortion, low noise, high slew rate operational amplifier series optimized and fully specified for high performance, high fidelity applications. Combining advanced leading-edge process technology with state-of-the-art circuit design, the LME49860 audio operational amplifiers deliver superior audio signal amplification for outstanding audio performance. The LME49860 combines extremely low voltage noise density (2.7nV/√Hz) with vanishingly low THD+N (0.00003%) to easily satisfy the most demanding audio applications. To ensure that the most challenging loads are driven without compromise, the LME49860 has a high slew rate of ±20V/μs and an output current capability of ±26mA. Further, dynamic range is maximized by an output stage that drives 2kΩ loads to within 1V of either power supply voltage and to within 1.4V when driving 600Ω loads.

The LME49860's outstanding CMRR (120dB), PSRR (120dB), and V_{OS} (0.1mV) give the amplifier excellent operational amplifier DC performance.

The LME49860 has a wide supply range of ±2.5V to ±22V. Over this supply range the LME49860 maintains excellent common-mode rejection, power supply rejection, and low input bias current. The LME49860 is unity gain stable. This Audio Operational Amplifier achieves outstanding AC performance while driving complex loads with values as high as 100pF.

The LME49860 is available in 8-lead narrow body SOIC and 8-lead Plastic DIP packages. Demonstration boards are available for each package.

Table 1. Key Specifications

	VALUE	UNIT
Power Supply Voltage Range	±2.5 to ±22	V
THD+N ($A_V = 1$, $V_{OUT} = 3V_{RMS}$, $f_{IN} = 1kHz$)		
$R_L = 2k\Omega$	0.00003	% (typ)
$R_L = 600\Omega$	0.00003%	(typ)
Input Noise Density	2.7	nV/√Hz (typ)
Slew Rate	±20	V/μs (typ)
Gain Bandwidth Product	55	MHz (typ)
Open Loop Gain ($R_L = 600\Omega$)	140	dB (typ)
Input Bias Current	10	nA (typ)
Input Offset Voltage	0.1	mV (typ)



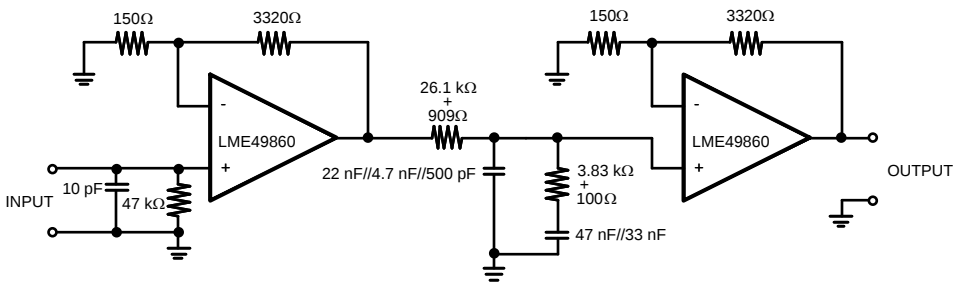
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Table 1. Key Specifications (continued)

DC Gain Linearity Error	0.000009%	
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Typical Application



Note: 1% metal film resistors, 5% polypropylene capacitors

Figure 1. Passively Equalized RIAA Phono Preamplifier

Connection Diagram

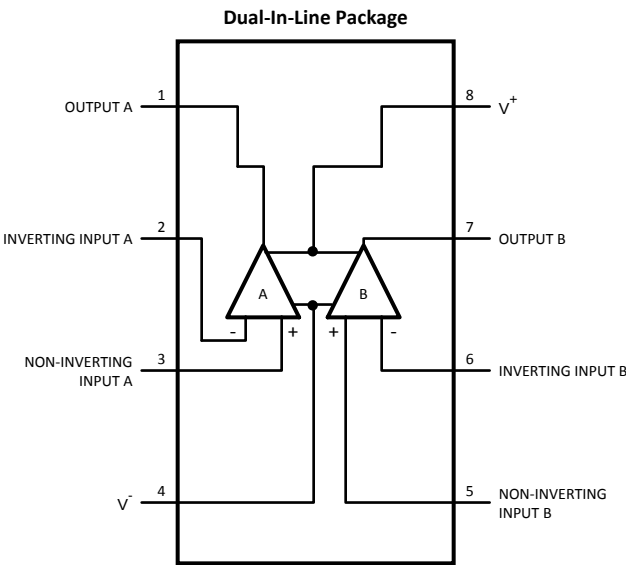


Figure 2. See NS Package Number — N08E



Figure 3. LME49860MA Top Mark
MA — Package code

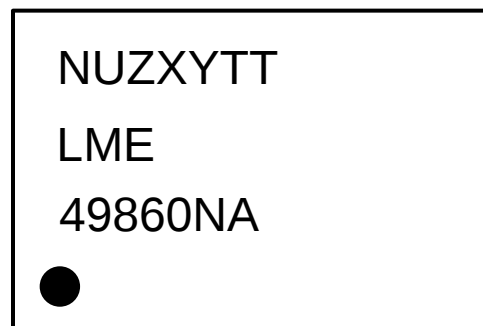


Figure 4. LME49860NA Top Mark
NA — Package code



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings ⁽¹⁾ ⁽²⁾

Power Supply Voltage ($V_S = V^+ - V^-$)	46V
Storage Temperature	–65°C to 150°C
Input Voltage	(V-) - 0.7V to (V+) + 0.7V
Output Short Circuit (Note 3)	Continuous
ESD Susceptibility (Note 4)	2000V
ESD Susceptibility (Note 5)	
Pins 1, 4, 7 and 8	200V
Pins 2, 3, 5 and 6	100V
Junction Temperature	150°C
Thermal Resistance	
θ_{JA} (SO)	145°C/W
θ_{JA} (NA)	102°C/W

- (1) *Absolute Maximum Ratings* indicate limits beyond which damage to the device may occur.
- (2) *Operating Ratings* indicate conditions for which the device is functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

Operating Ratings

Temperature Range	
$T_{\text{MIN}} \leq T_A \leq T_{\text{MAX}}$	$-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$
Supply Voltage Range	$\pm 2.5\text{V} \leq V_S \leq \pm 22\text{V}$

Electrical Characteristics for the LME49860 ⁽¹⁾

The following specifications apply for $V_S = \pm 18V$ and $\pm 22V$, $R_L = 2k\Omega$, $R_{SOURCE} = 10\Omega$, $f_{IN} = 1kHz$, $T_A = 25^\circ C$, unless otherwise specified.

Symbol	Parameter	Conditions	LME49860		Units (Limits)
			Typical	Limit	
			(2)	(3)	
THD+N	Total Harmonic Distortion + Noise	$A_V = 1$, $V_{OUT} = 3V_{rms}$ $R_L = 2k\Omega$ $R_L = 600\Omega$	0.00003 0.00003	0.00009	% (max)
IMD	Intermodulation Distortion	$A_V = 1$, $V_{OUT} = 3V_{RMS}$ Two-tone, 60Hz & 7kHz 4:1	0.00005		%
GBWP	Gain Bandwidth Product		55	45	MHz (min)
SR	Slew Rate		± 20	± 15	V/ μs (min)
FPBW	Full Power Bandwidth	$V_{OUT} = 1V_{P-P}$, $-3dB$ referenced to output magnitude at $f = 1kHz$	10		MHz
t_s	Settling time	$A_V = -1$, 10V step, $C_L = 100pF$ 0.1% error range	1.2		μs
e_n	Equivalent Input Noise Voltage	$f_{BW} = 20Hz$ to $20kHz$	0.34	0.65	μV_{RMS} (max)
	Equivalent Input Noise Density	$f = 1kHz$ $f = 10Hz$	2.7 6.4	4.7	$nV/\sqrt{Hz}$ (max)
i_n	Current Noise Density	$f = 1kHz$ $f = 10Hz$	1.6 3.1		$pA/\sqrt{Hz}$
V_{OS}	Offset Voltage	$V_S = \pm 18V$	± 0.12	± 0.7	mV (max)
		$V_S = \pm 22V$	± 0.14	± 0.7	mV (max)
$\Delta V_{OS}/\Delta Temp$	Average Input Offset Voltage Drift vs Temperature	$-40^\circ C \leq T_A \leq 85^\circ C$	0.2		$\mu V/^\circ C$
PSRR	Average Input Offset Voltage Shift vs Power Supply Voltage	(Note 8) $V_S = \pm 18V$, $\Delta V_S = 24V$ $V_S = \pm 22V$, $\Delta V_S = 30V$	120 120	110	dB dB (min)
ISO _{CH-CH}	Channel-to-Channel Isolation	$f_{IN} = 1kHz$ $f_{IN} = 20kHz$	118 112		dB
I_B	Input Bias Current	$V_{CM} = 0V$	10	72	nA (max)
$\Delta I_{OS}/\Delta Temp$	Input Bias Current Drift vs Temperature	$-40^\circ C \leq T_A \leq 85^\circ C$	0.1		nA/ $^\circ C$
I_{OS}	Input Offset Current	$V_{CM} = 0V$	11	65	nA (max)
V_{IN-CM}	Common-Mode Input Voltage Range	$V_S = \pm 18V$	+17.1 -16.9	(V+) – 2.0 (V-) + 2.0	V (min) V (min)
		$V_S = \pm 22V$	+21.0 -20.8	(V+) – 2.0 (V-) + 2.0	V (min) V (min)
CMRR	Common-Mode Rejection	$V_S = \pm 18V$ $-12V \leq V_{CM} \leq 12V$	120		dB
		$V_S = \pm 22V$ $-15V \leq V_{CM} \leq 15V$	120	110	dB (min)
Z_{IN}	Differential Input Impedance		30		k Ω
	Common Mode Input Impedance	$-10V < V_{cm} < 10V$	1000		M Ω

(1) *Absolute Maximum Ratings* indicate limits beyond which damage to the device may occur.

(2) Typical specifications are specified at $+25^\circ C$ and represent the most likely parametric norm.

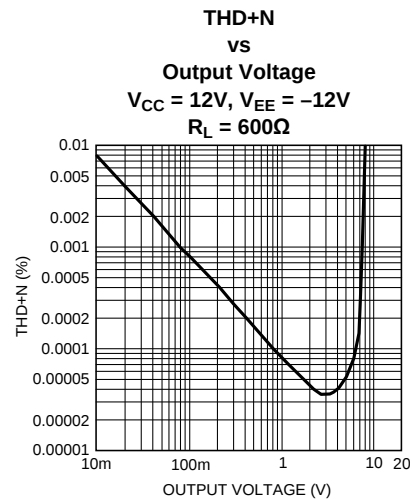
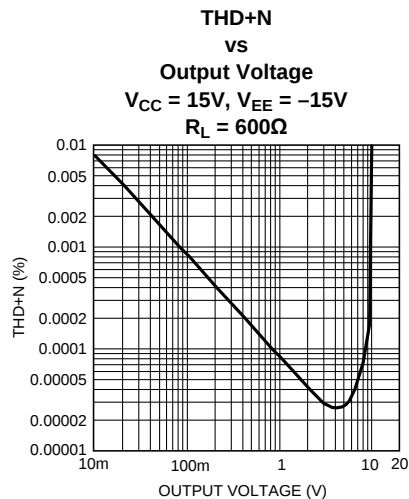
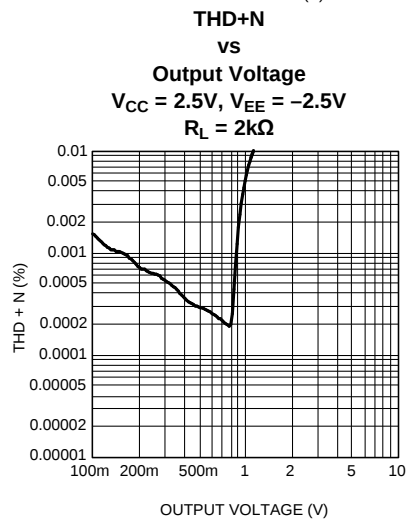
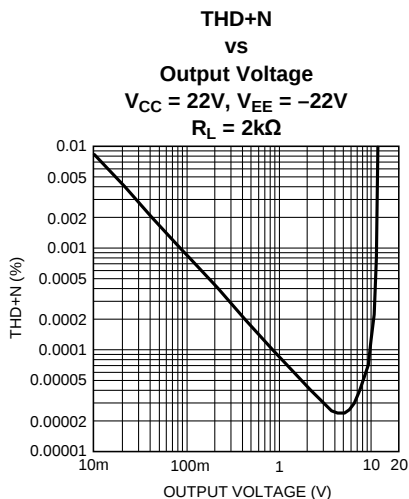
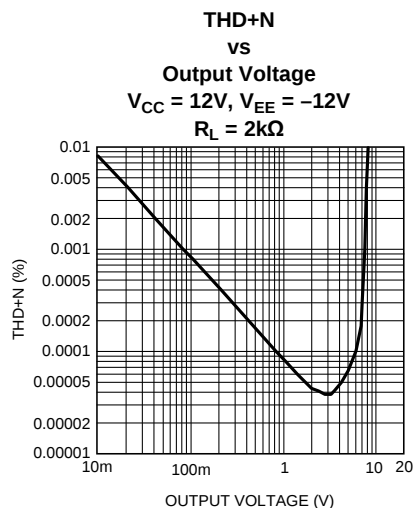
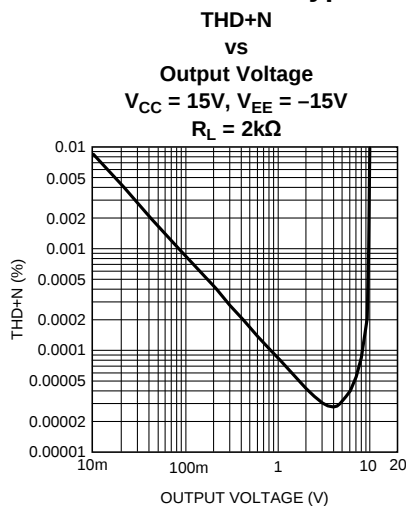
(3) Tested limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

Electrical Characteristics for the LME49860 ⁽¹⁾ (continued)

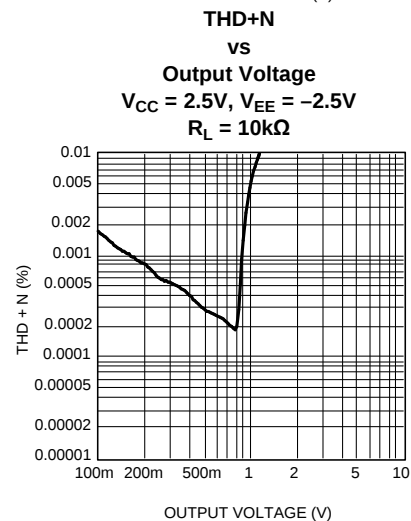
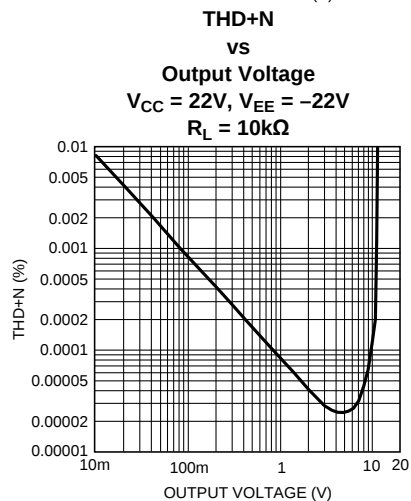
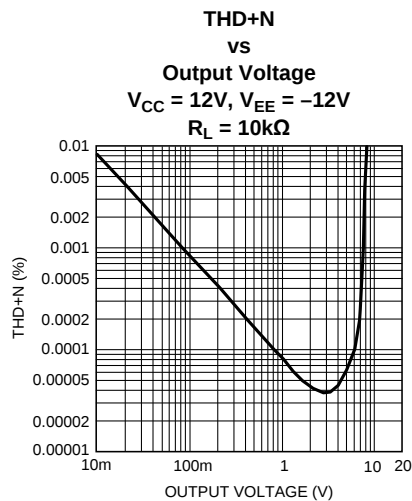
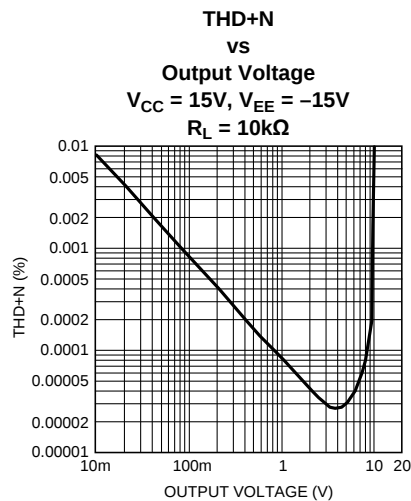
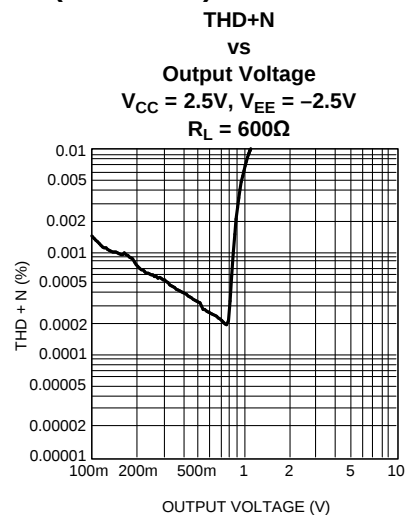
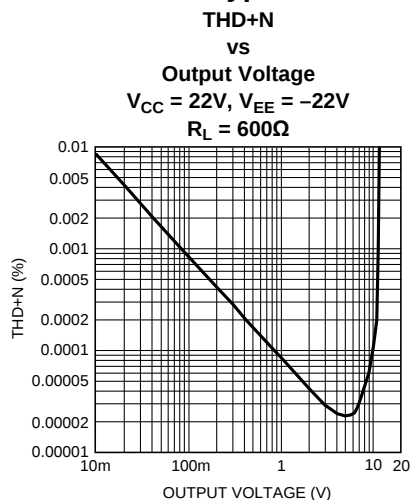
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Symbol	Parameter	Conditions	LME49860		Units (Limits)
			Typical	Limit	
			(2)	(3)	
A_{VOL}	Open Loop Voltage Gain	$V_S = \pm 18V$ $-12V \leq V_{out} \leq 12V$ $R_L = 600\Omega$ $R_L = 2k\Omega$ $R_L = 10k\Omega$	140 140 140		dB dB dB
		$V_S = \pm 22V$ $-15V \leq V_{out} \leq 15V$ $R_L = 600\Omega$ $R_L = 2k\Omega$ $R_L = 10k\Omega$	140 140 140	125	dB (min) dB dB
V_{OUTMAX}	Maximum Output Voltage Swing	$R_L = 600\Omega$ $V_S = \pm 18V$ $V_S = \pm 22V$	± 16.7 ± 20.4	± 19.0	V V (min)
		$R_L = 2k\Omega$ $V_S = \pm 18V$ $V_S = \pm 22V$	± 17.0 ± 21.0		V V
		$R_L = 10k\Omega$ $V_S = \pm 18V$ $V_S = \pm 22V$	± 17.1 ± 21.2		V V
I_{OUT}	Output Current	$R_L = 600\Omega$ $V_S = \pm 20V$ $V_S = \pm 22V$	± 31 ± 37	± 30	mA mA (min)
I_{OUT-CC}	Instantaneous Short Circuit Current		+53 -42		mA
R_{OUT}	Output Impedance	$f_{IN} = 10kHz$ Closed-Loop Open-Loop	0.01 13		Ω
C_{LOAD}	Capacitive Load Drive Overshoot	100pF	16		%
I_S	Total Quiescent Current	$I_{OUT} = 0mA$ $V_S = \pm 18V$ $V_S = \pm 22V$	10.2 10.5	13	mA mA (max)

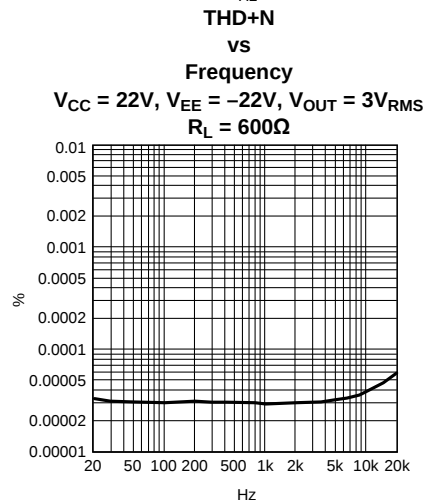
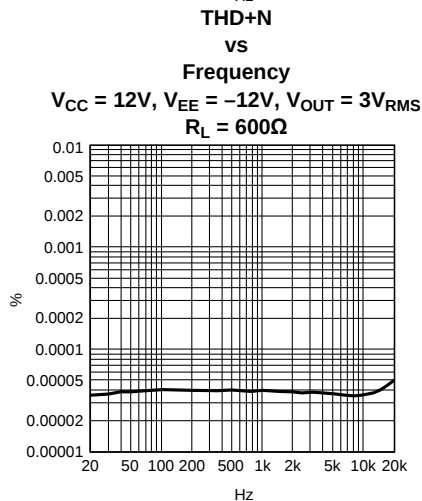
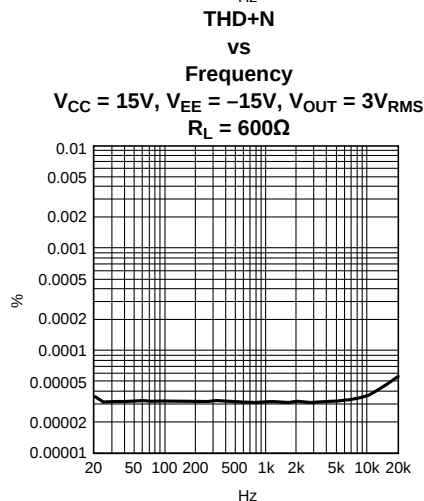
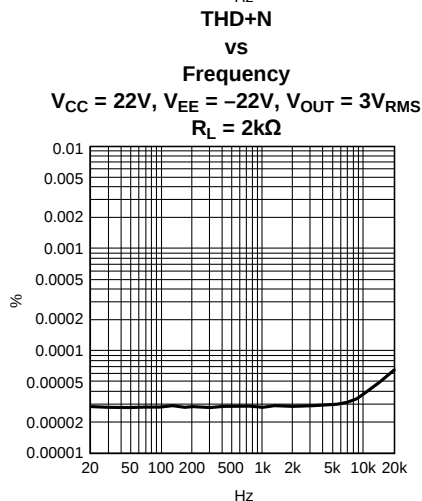
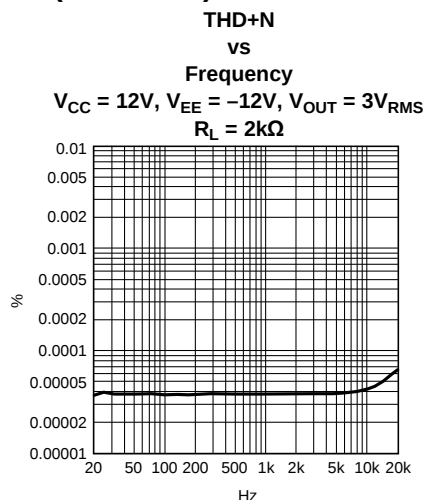
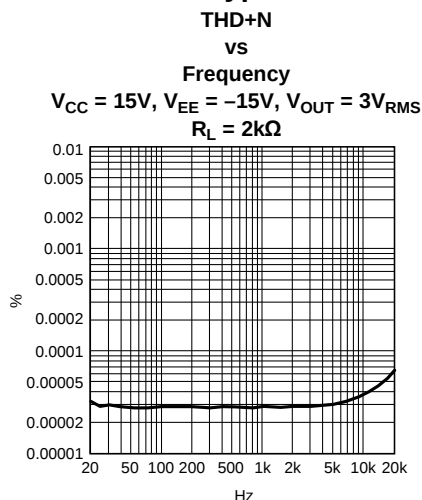
Typical Performance Characteristics

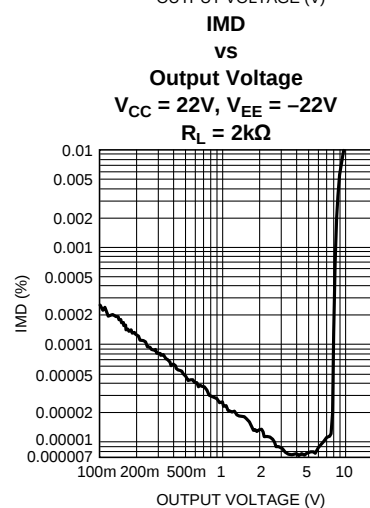
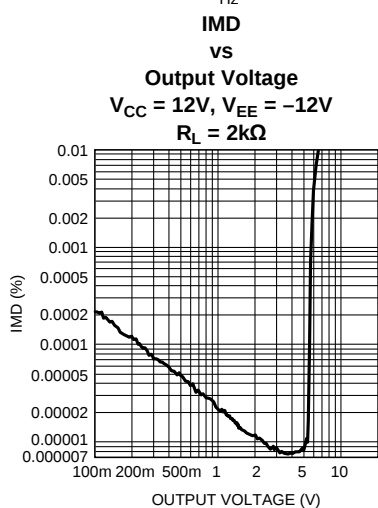
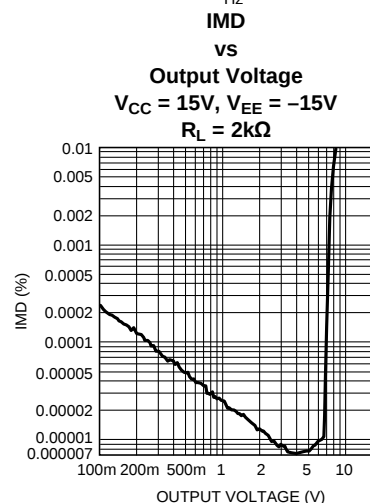
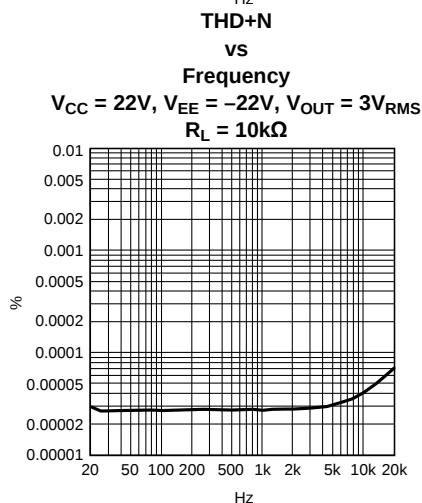
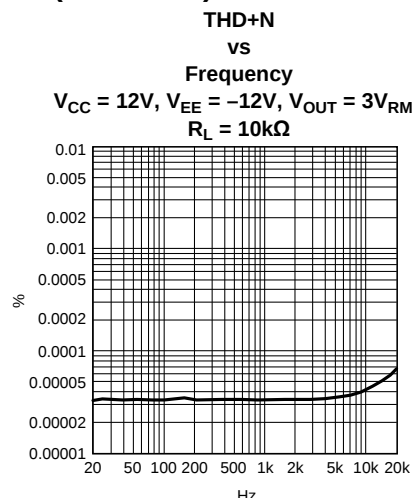
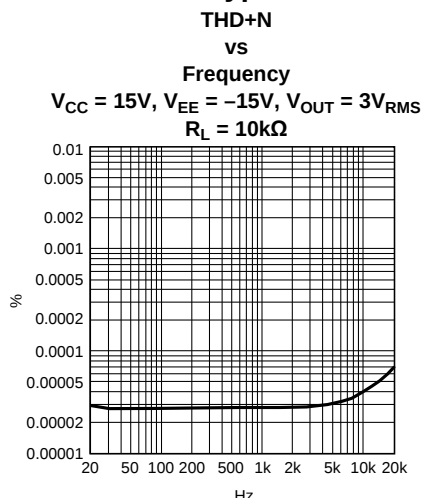


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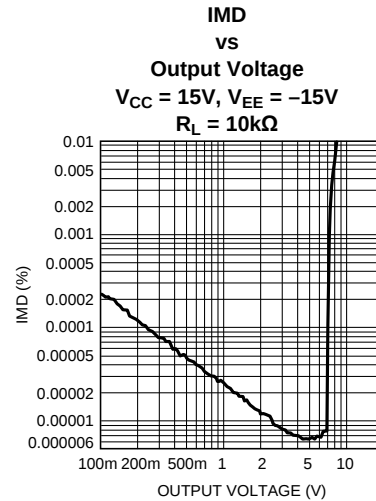
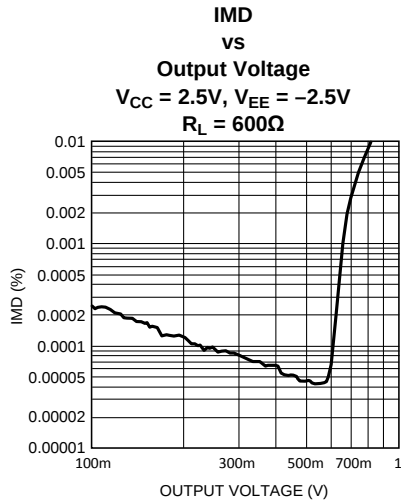
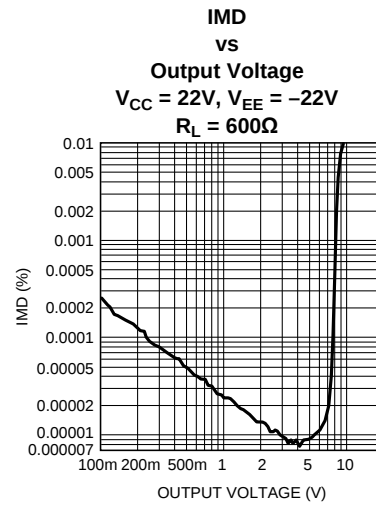
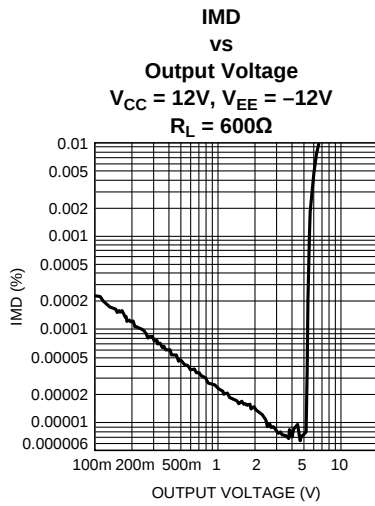
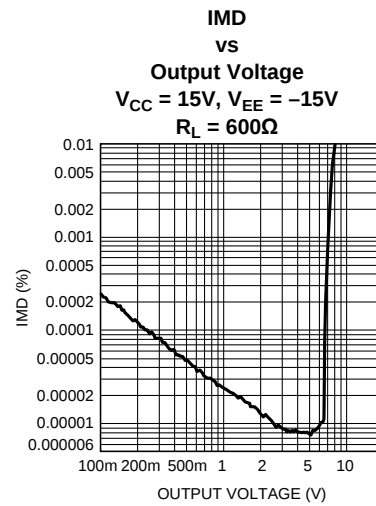
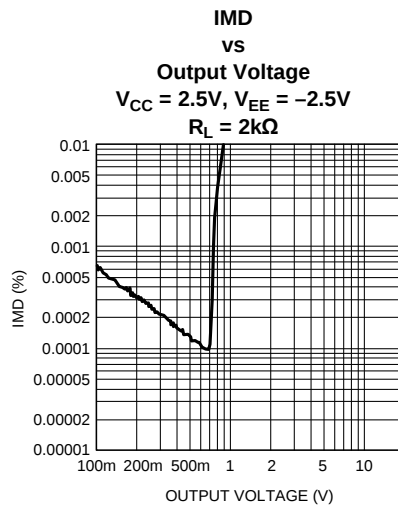


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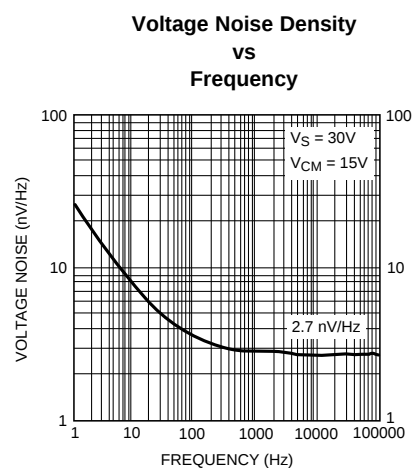
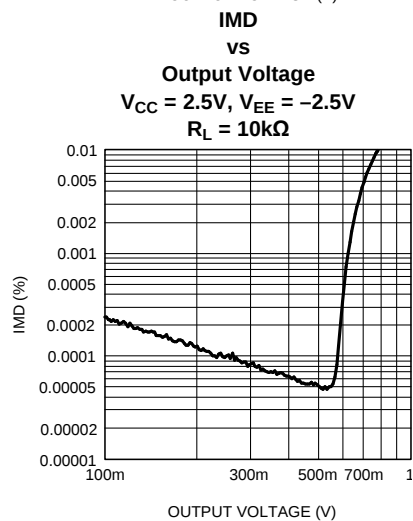
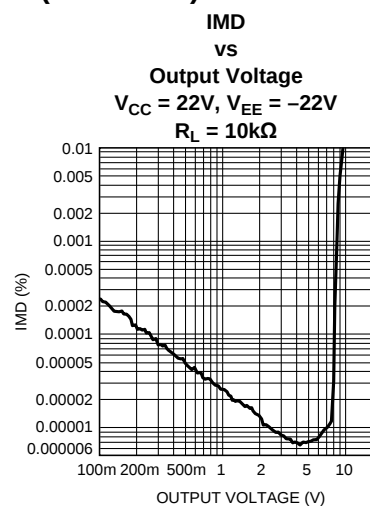
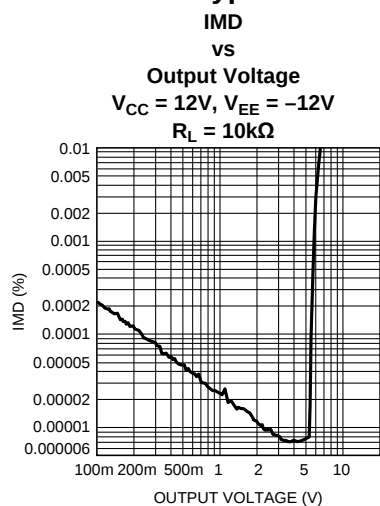


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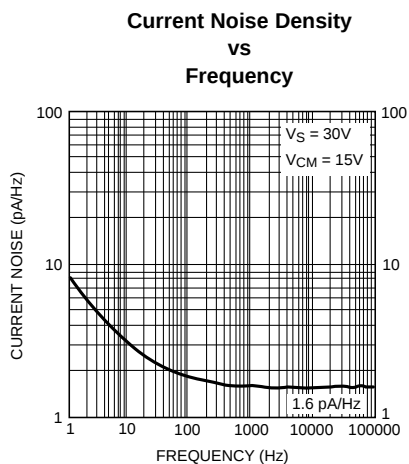
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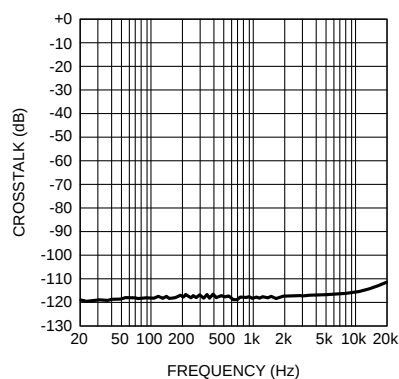
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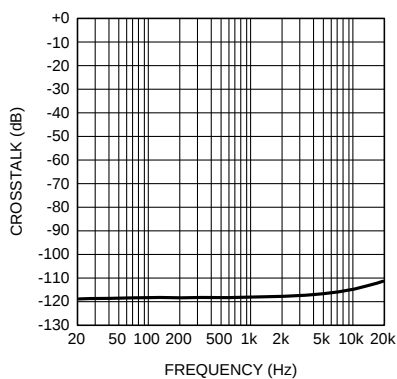
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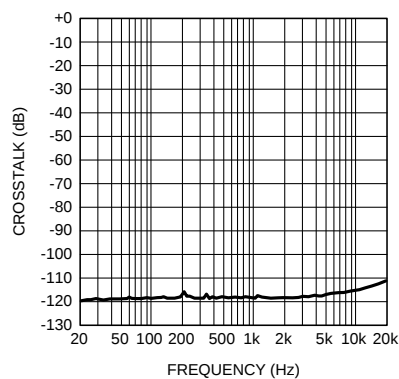
**Crosstalk
vs
Frequency**
 $V_{CC} = 15V$, $V_{EE} = -15V$, $V_{OUT} = 3V_{RMS}$
 $A_V = 0dB$, $R_L = 2k\Omega$



**Crosstalk
vs
Frequency**
 $V_{CC} = 15V$, $V_{EE} = -15V$, $V_{OUT} = 10V_{RMS}$
 $A_V = 0dB$, $R_L = 2k\Omega$



**Crosstalk
vs
Frequency**
 $V_{CC} = 12V$, $V_{EE} = -12V$, $V_{OUT} = 3V_{RMS}$
 $A_V = 0dB$, $R_L = 2k\Omega$

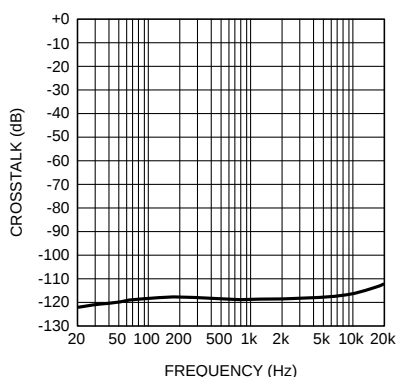


Typical Performance Characteristics (continued)

Crosstalk
vs

Frequency

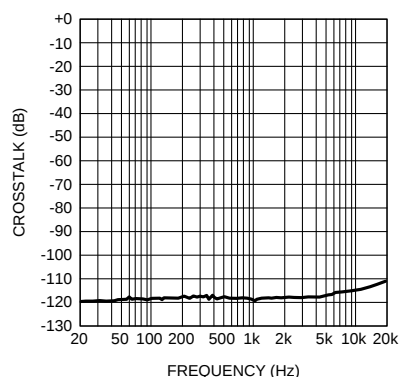
$V_{CC} = 12V$, $V_{EE} = -12V$, $V_{OUT} = 10V_{RMS}$
 $A_V = 0dB$, $R_L = 2k\Omega$



Crosstalk
vs

Frequency

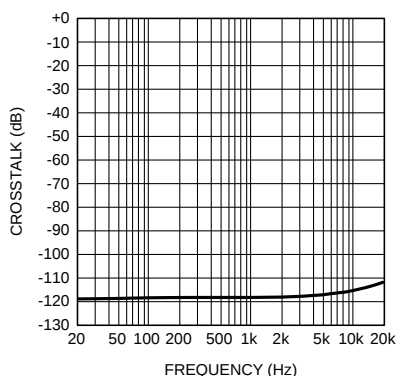
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 $A_V = 0dB$, $R_L = 2k\Omega$



Crosstalk
vs

Frequency

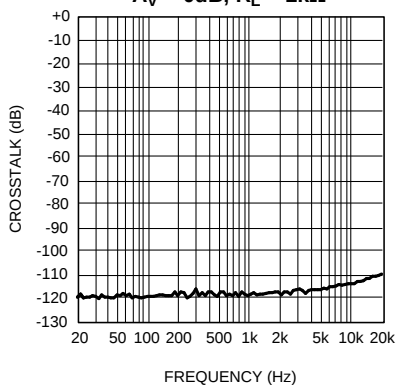
$V_{CC} = 22V$, $V_{EE} = -22V$, $V_{OUT} = 10V_{RMS}$
 $A_V = 0dB$, $R_L = 2k\Omega$



Crosstalk
vs

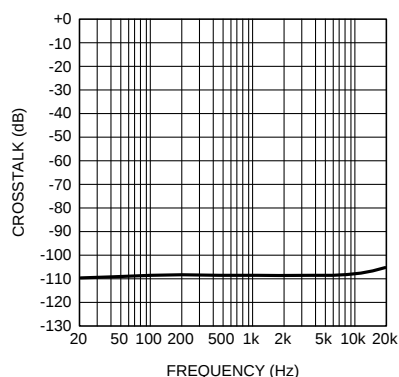
Frequency

$V_{CC} = 2.5V$, $V_{EE} = -2.5V$, $V_{OUT} = 1V_{RMS}$
 $A_V = 0dB$, $R_L = 2k\Omega$

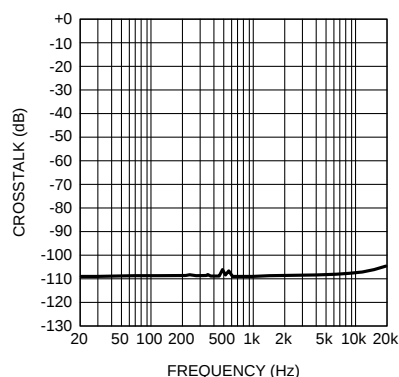


Typical Performance Characteristics (continued)

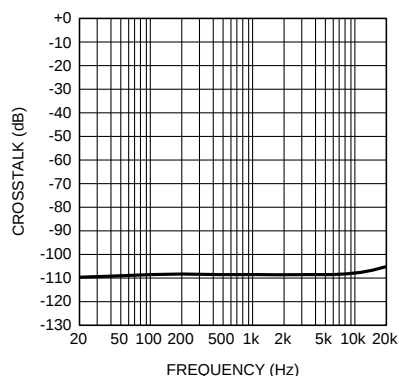
**Crosstalk
vs
Frequency**
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 $A_V = 0dB$, $R_L = 600\Omega$



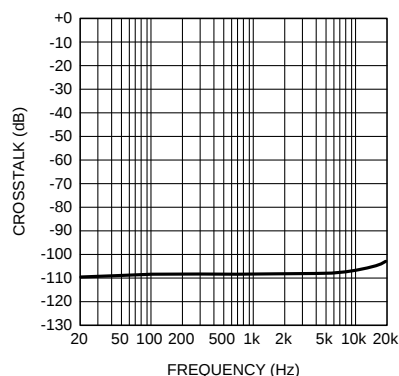
**Crosstalk
vs
Frequency**
 $V_{CC} = 15V$, $V_{EE} = -15V$, $V_{OUT} = 10V_{RMS}$
 $A_V = 0dB$, $R_L = 600\Omega$



**Crosstalk
vs
Frequency**
 $V_{CC} = 12V$, $V_{EE} = -12V$, $V_{OUT} = 3V_{RMS}$
 $A_V = 0dB$, $R_L = 600\Omega$



**Crosstalk
vs
Frequency**
 $V_{CC} = 12V$, $V_{EE} = -12V$, $V_{OUT} = 10V_{RMS}$
 $A_V = 0dB$, $R_L = 600\Omega$

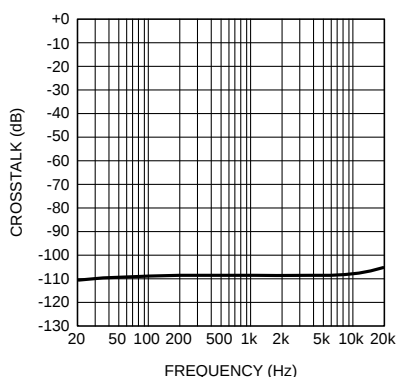


Typical Performance Characteristics (continued)

Crosstalk
vs

Frequency

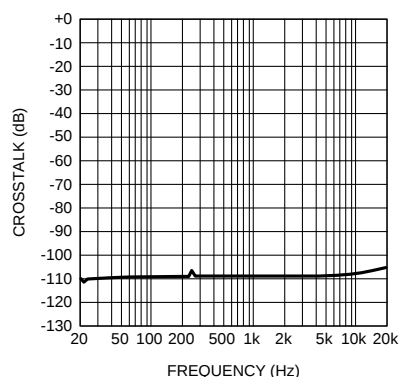
$V_{CC} = 22V$, $V_{EE} = -22V$, $V_{OUT} = 3V_{RMS}$
 $A_V = 0dB$, $R_L = 600\Omega$



Crosstalk
vs

Frequency

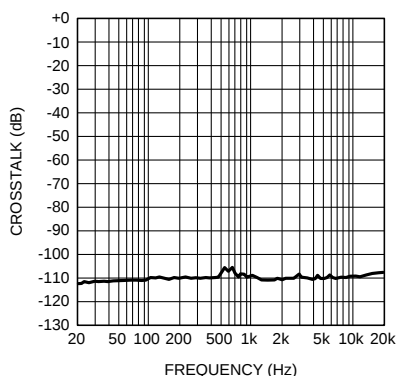
$V_{CC} = 22V$, $V_{EE} = -22V$, $V_{OUT} = 10V_{RMS}$
 $A_V = 0dB$, $R_L = 600\Omega$



Crosstalk
vs

Frequency

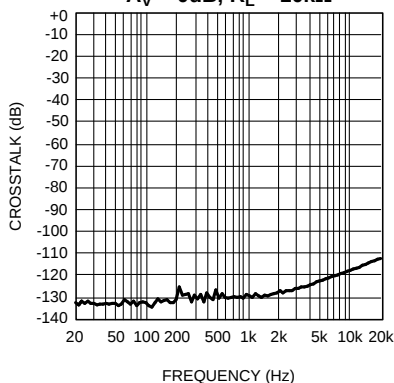
$V_{CC} = 2.5V$, $V_{EE} = -2.5V$, $V_{OUT} = 1V_{RMS}$
 $A_V = 0dB$, $R_L = 600\Omega$



Crosstalk
vs

Frequency

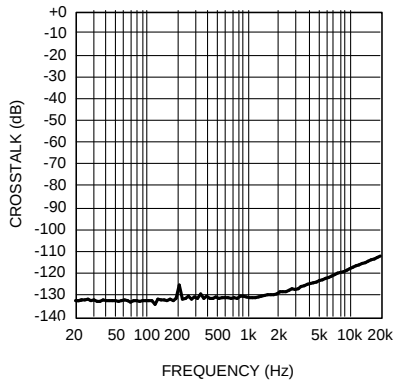
$V_{CC} = 15V$, $V_{EE} = -15V$, $V_{OUT} = 3V_{RMS}$
 $A_V = 0dB$, $R_L = 10k\Omega$



Typical Performance Characteristics (continued)

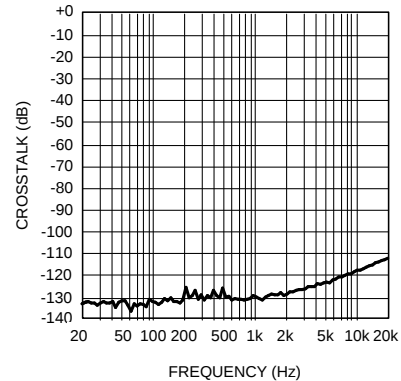
**Crosstalk
vs
Frequency**

$V_{CC} = 15V$, $V_{EE} = -15V$, $V_{OUT} = 10V_{RMS}$
 $A_V = 0dB$, $R_L = 10k\Omega$



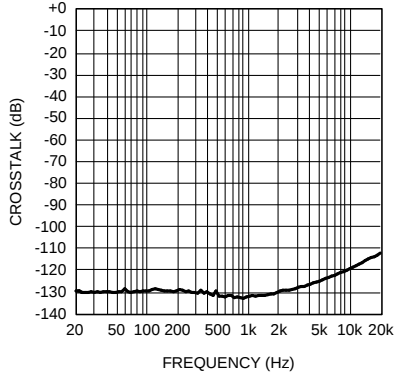
**Crosstalk
vs
Frequency**

$V_{CC} = 12V$, $V_{EE} = -12V$, $V_{OUT} = 3V_{RMS}$
 $A_V = 0dB$, $R_L = 10k\Omega$



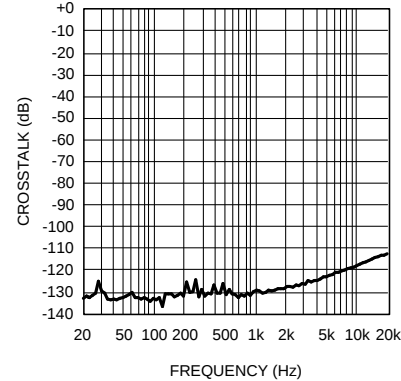
**Crosstalk
vs
Frequency**

$V_{CC} = 12V$, $V_{EE} = -12V$, $V_{OUT} = 10V_{RMS}$
 $A_V = 0dB$, $R_L = 10k\Omega$



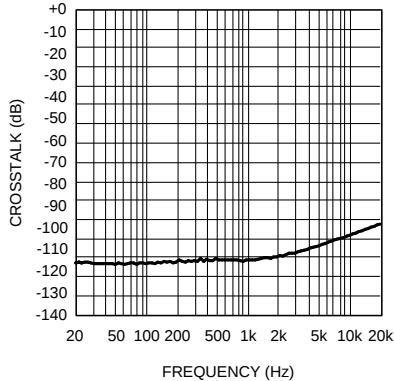
**Crosstalk
vs
Frequency**

$V_{CC} = 22V$, $V_{EE} = -22V$, $V_{OUT} = 3V_{RMS}$
 $A_V = 0dB$, $R_L = 10k\Omega$



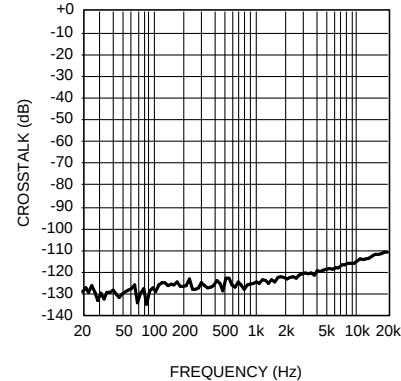
**Crosstalk
vs
Frequency**

$V_{CC} = 22V$, $V_{EE} = -22V$, $V_{OUT} = 10V_{RMS}$
 $A_V = 0dB$, $R_L = 10k\Omega$

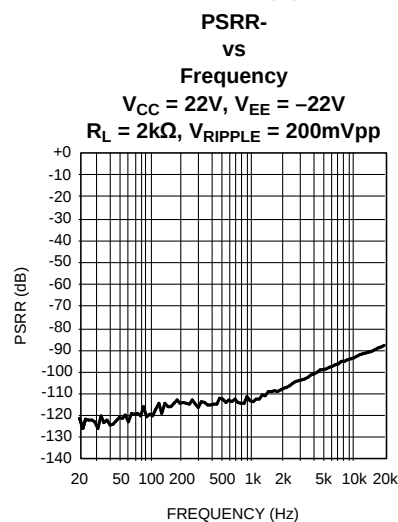
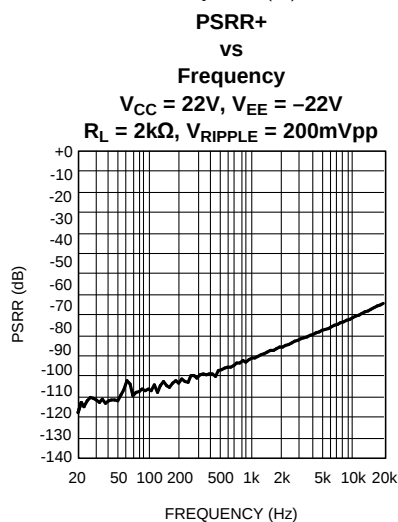
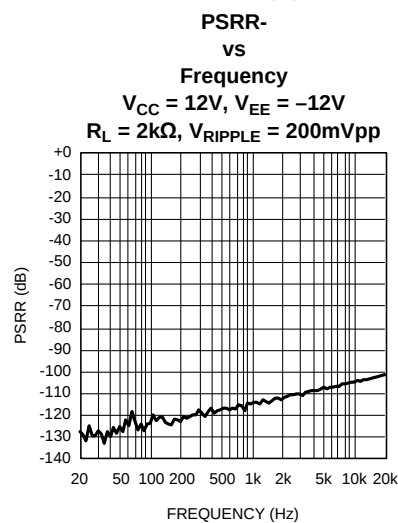
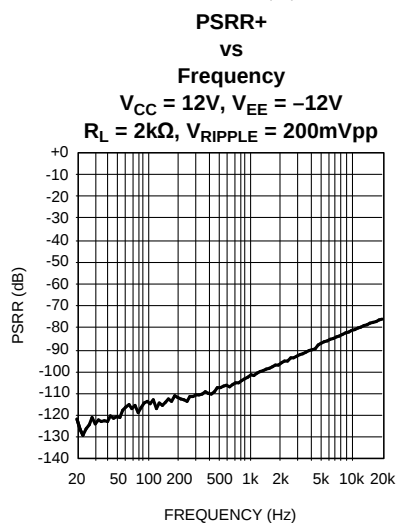
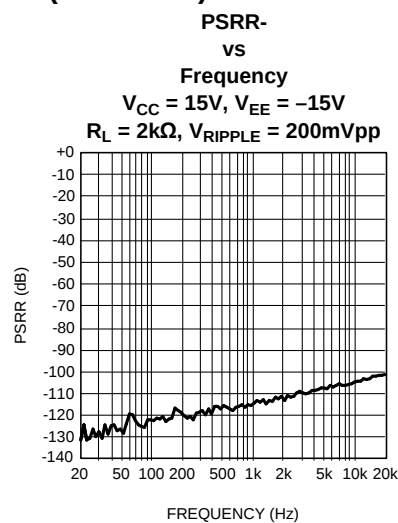
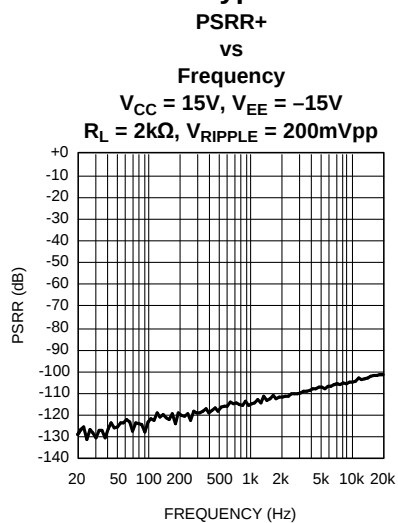


**Crosstalk
vs
Frequency**

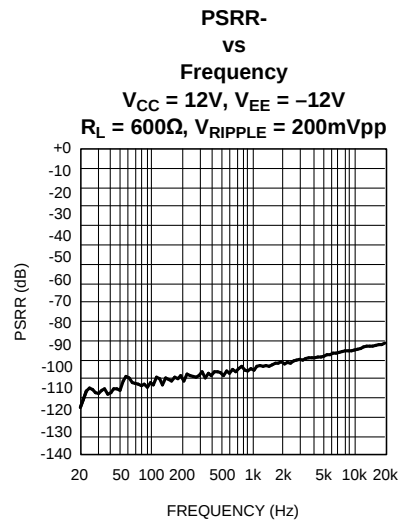
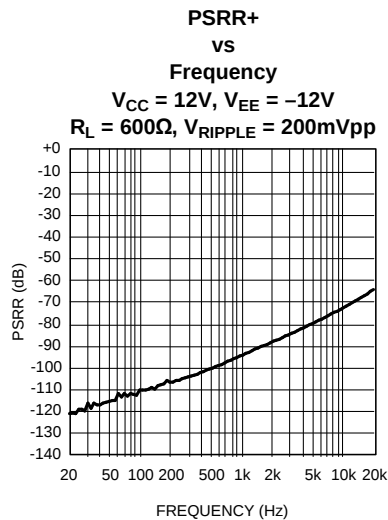
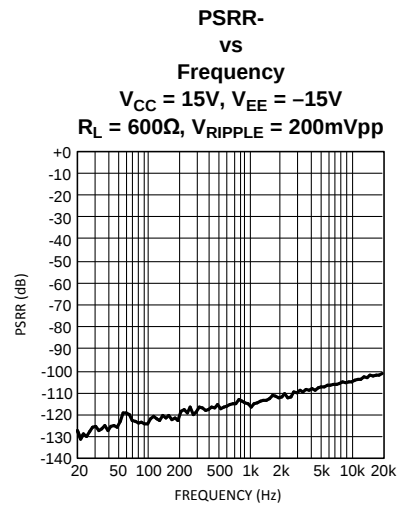
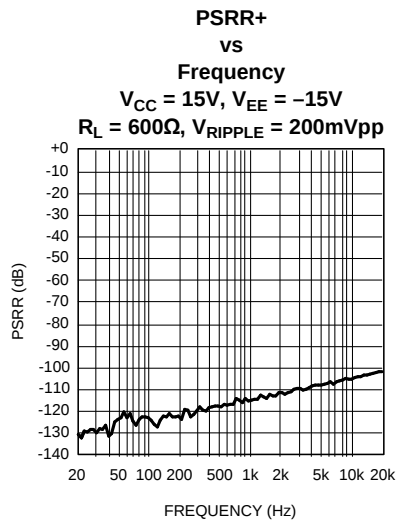
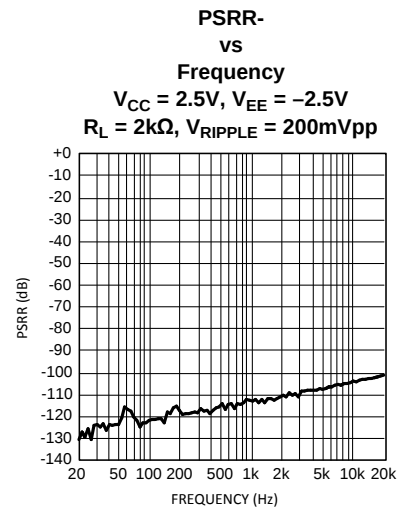
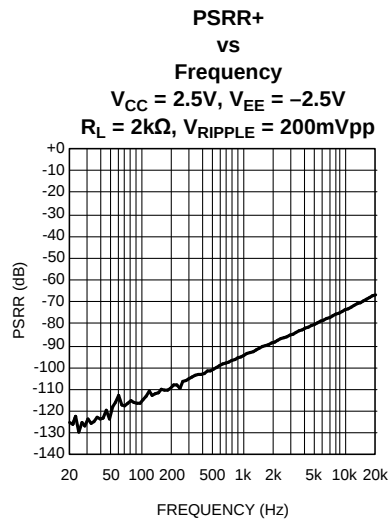
$V_{CC} = 2.5V$, $V_{EE} = -2.5V$, $V_{OUT} = 1V_{RMS}$
 $A_V = 0dB$, $R_L = 10k\Omega$



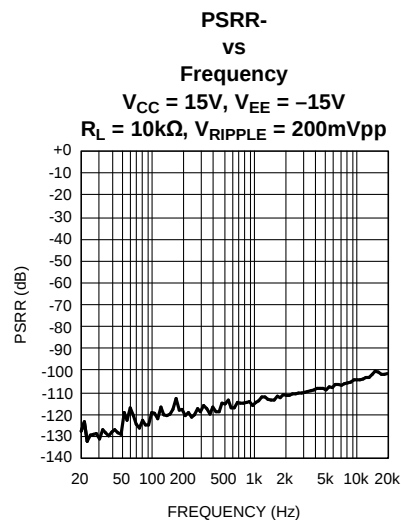
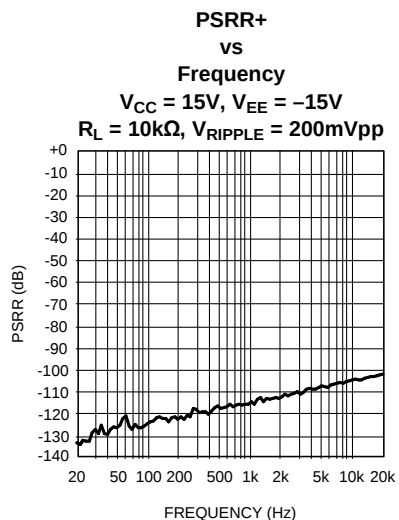
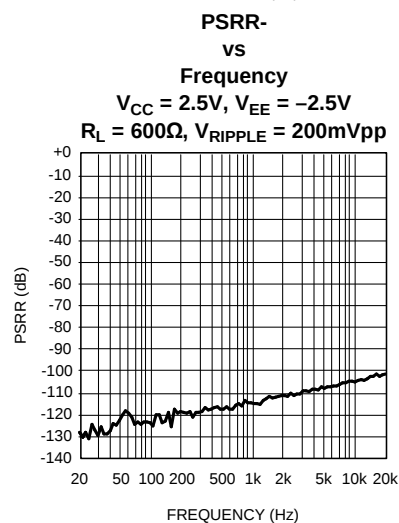
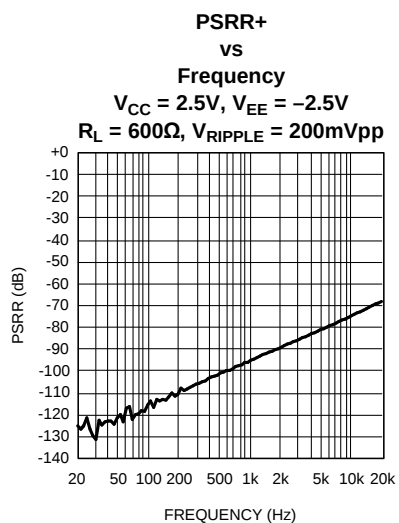
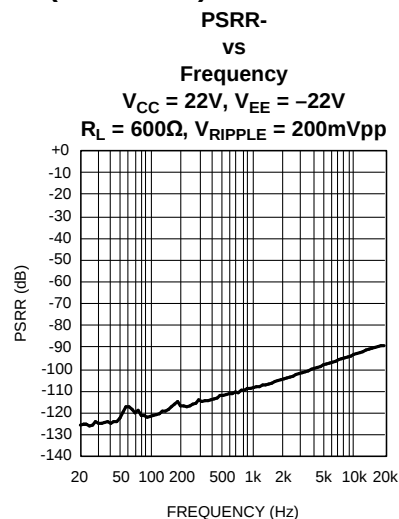
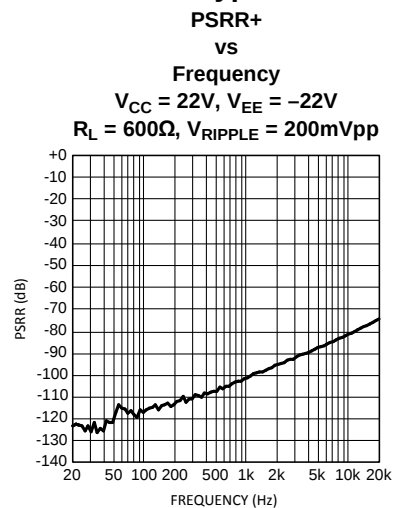
Typical Performance Characteristics (continued)



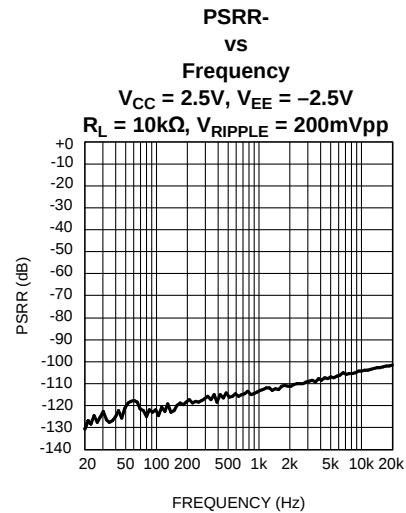
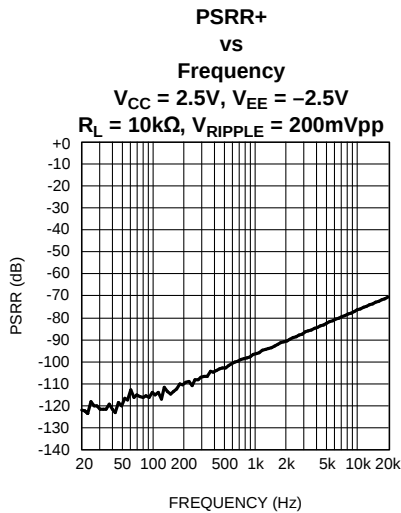
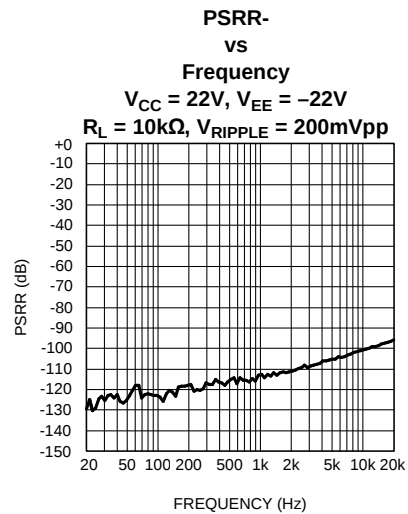
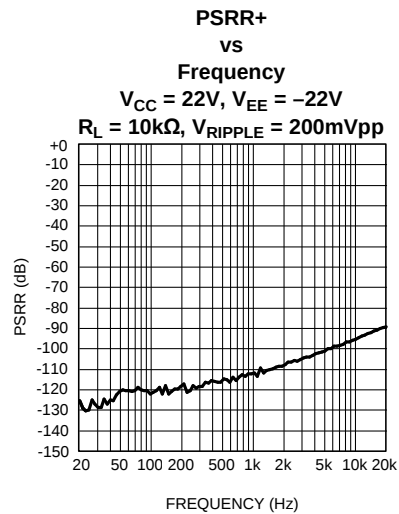
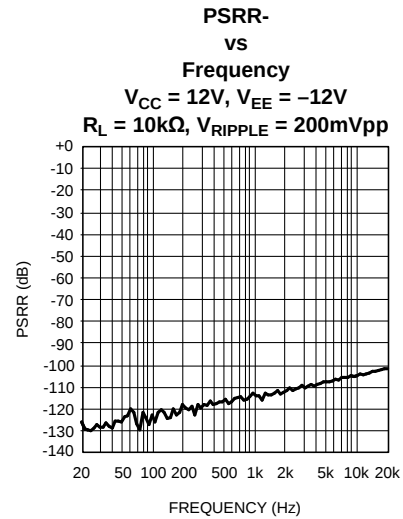
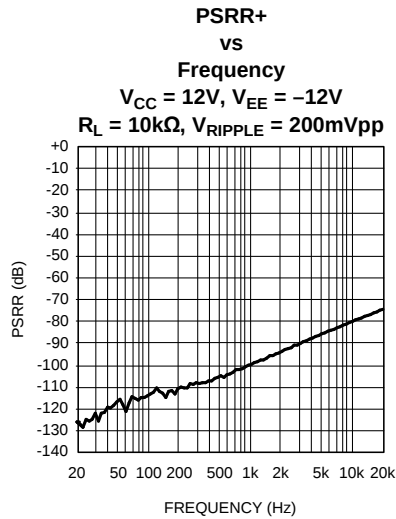
Typical Performance Characteristics (continued)

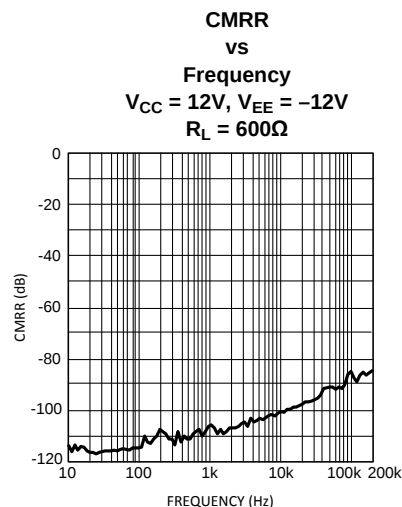
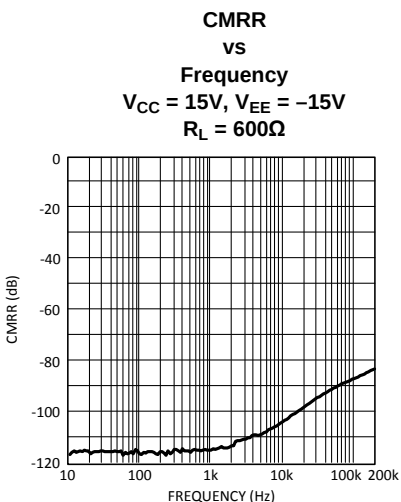
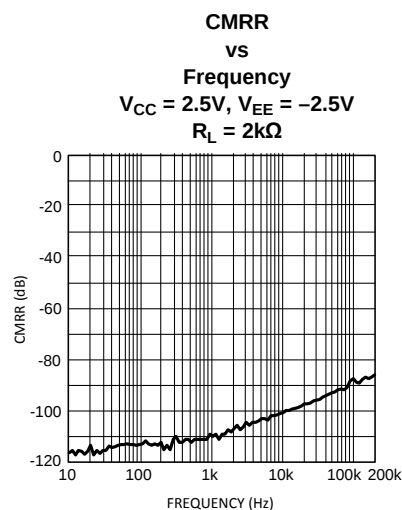
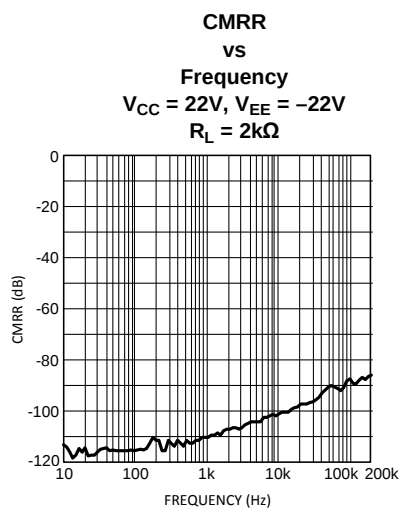
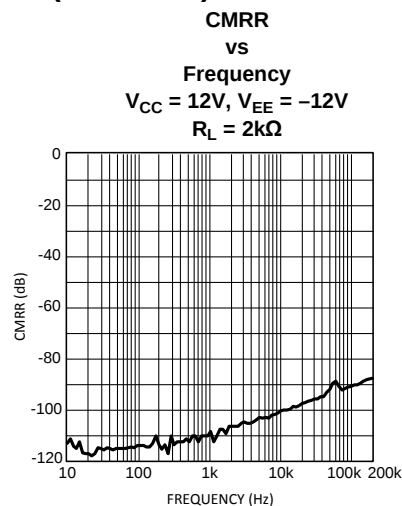
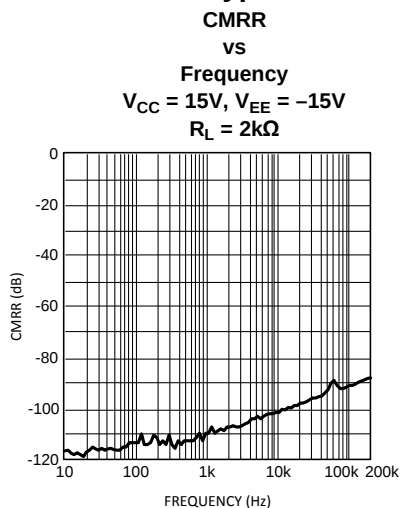


Typical Performance Characteristics (continued)

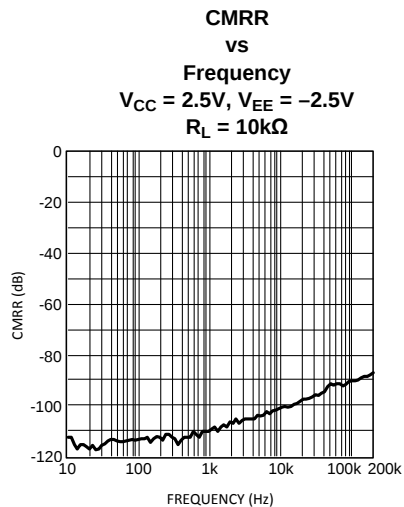
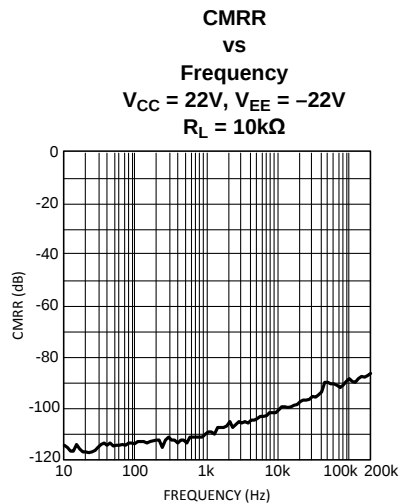
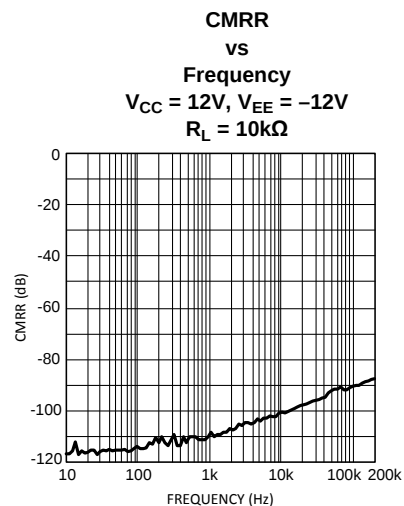
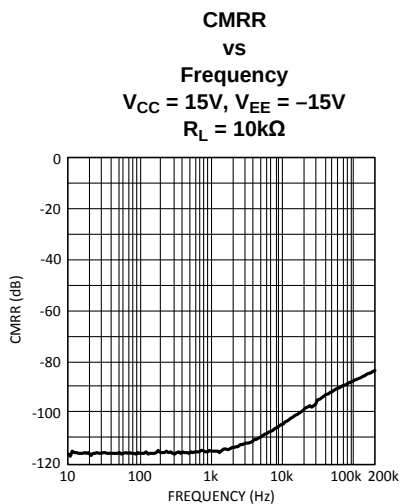
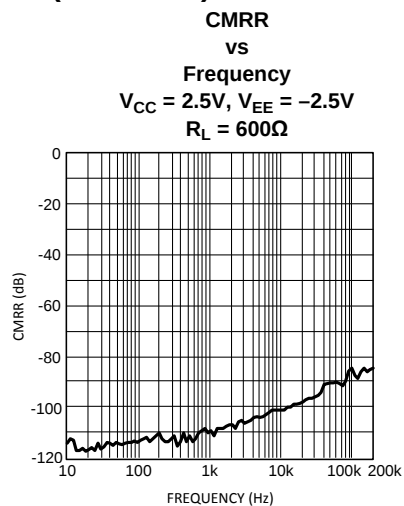
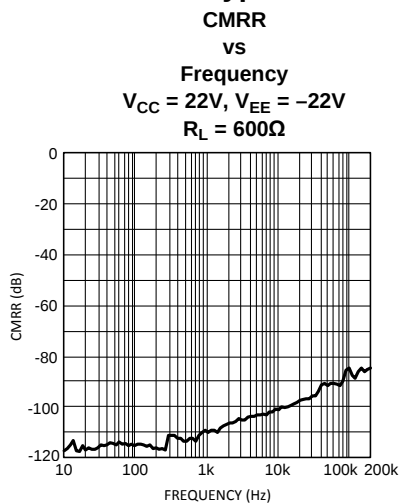


Typical Performance Characteristics (continued)

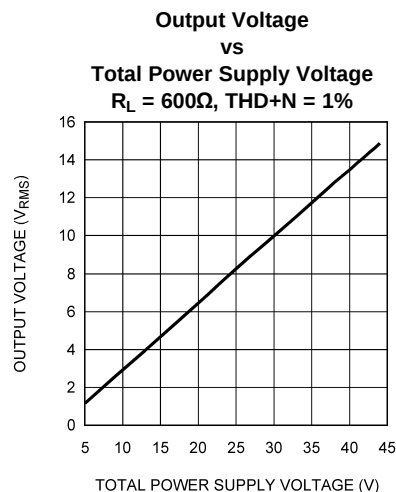
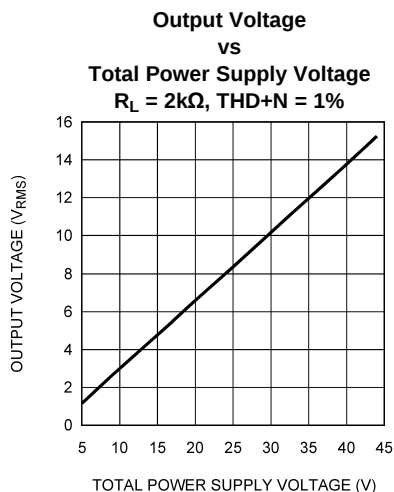
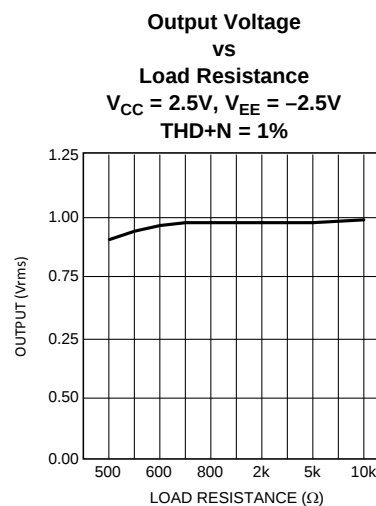
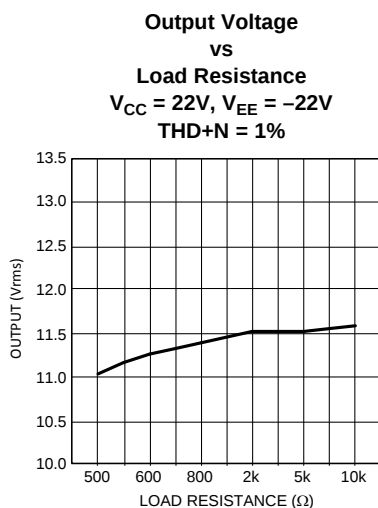
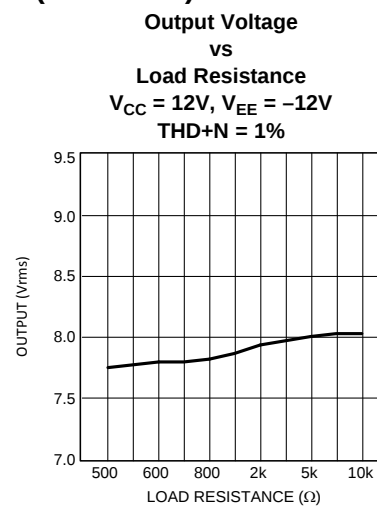
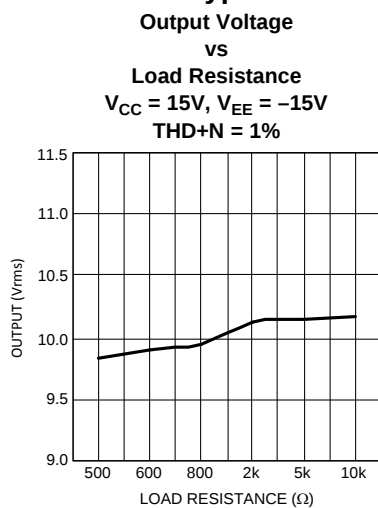


Typical Performance Characteristics (continued)

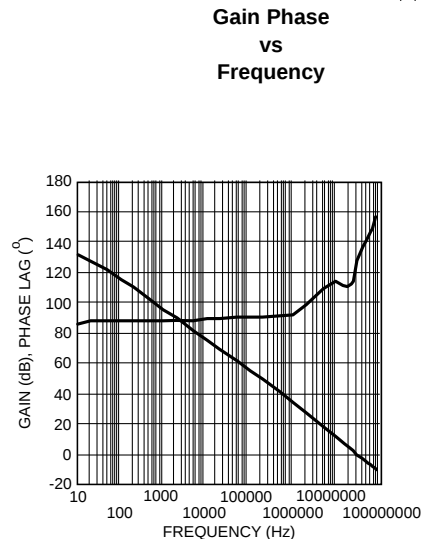
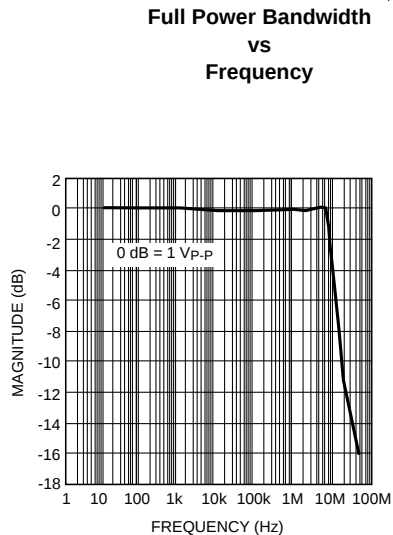
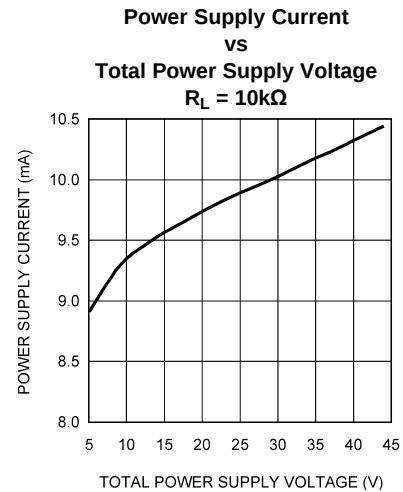
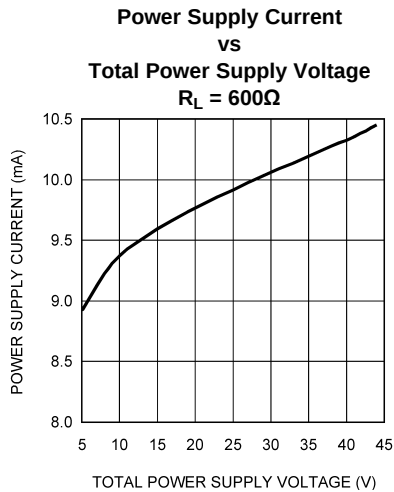
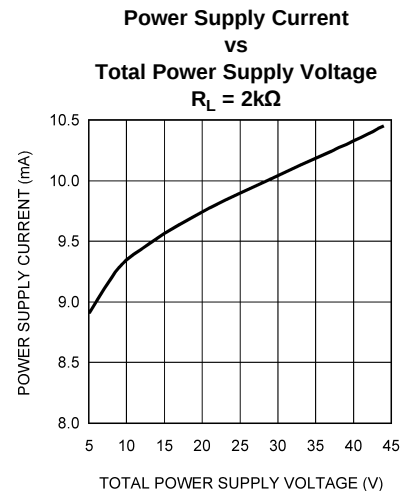
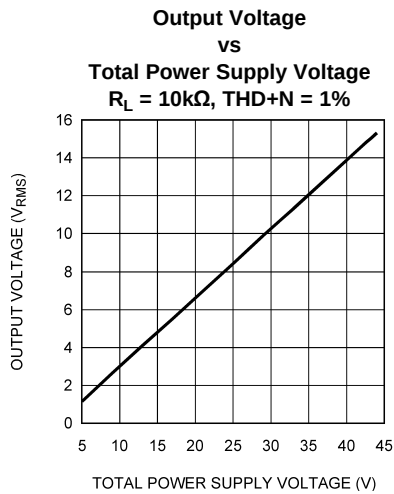
Typical Performance Characteristics (continued)



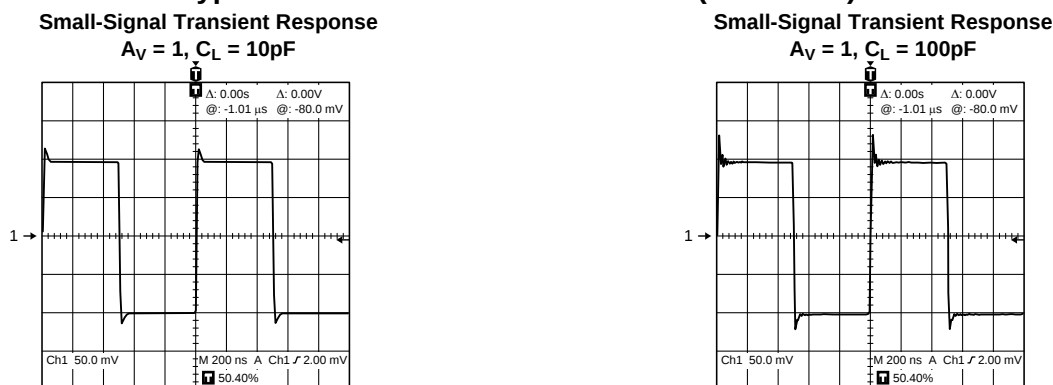
Typical Performance Characteristics (continued)



Typical Performance Characteristics (continued)



Typical Performance Characteristics (continued)



Application Information

DISTORTION MEASUREMENTS

The vanishingly low residual distortion produced by LME49860 is below the capabilities of all commercially available equipment. This makes distortion measurements just slightly more difficult than simply connecting a distortion meter to the amplifier's inputs and outputs. The solution, however, is quite simple: an additional resistor. Adding this resistor extends the resolution of the distortion measurement equipment.

The LME49860's low residual distortion is an input referred internal error. As shown in Figure 1, adding the 10Ω resistor connected between the amplifier's inverting and non-inverting inputs changes the amplifier's noise gain. The result is that the error signal (distortion) is amplified by a factor of 101. Although the amplifier's closed-loop gain is unaltered, the feedback available to correct distortion errors is reduced by 101, which means that measurement resolution increases by 101. To ensure minimum effects on distortion measurements, keep the value of R_1 low as shown in Figure 1.

This technique is verified by duplicating the measurements with high closed loop gain and/or making the measurements at high frequencies. Doing so produces distortion components that are within the measurement equipment's capabilities. This datasheet's THD+N and IMD values were generated using the above described circuit connected to an Audio Precision System Two Cascade.

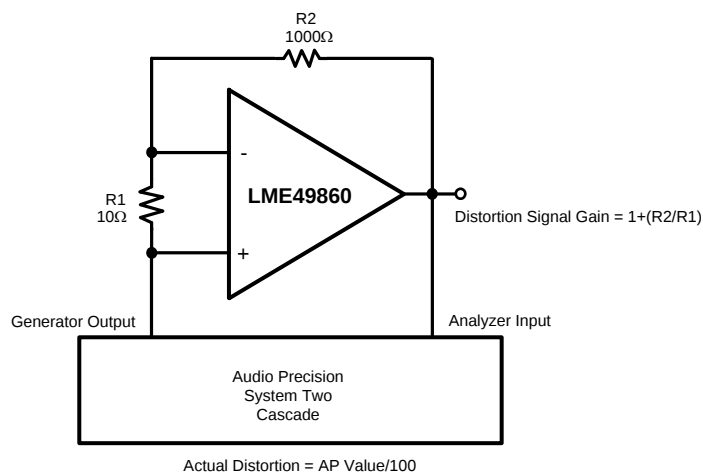
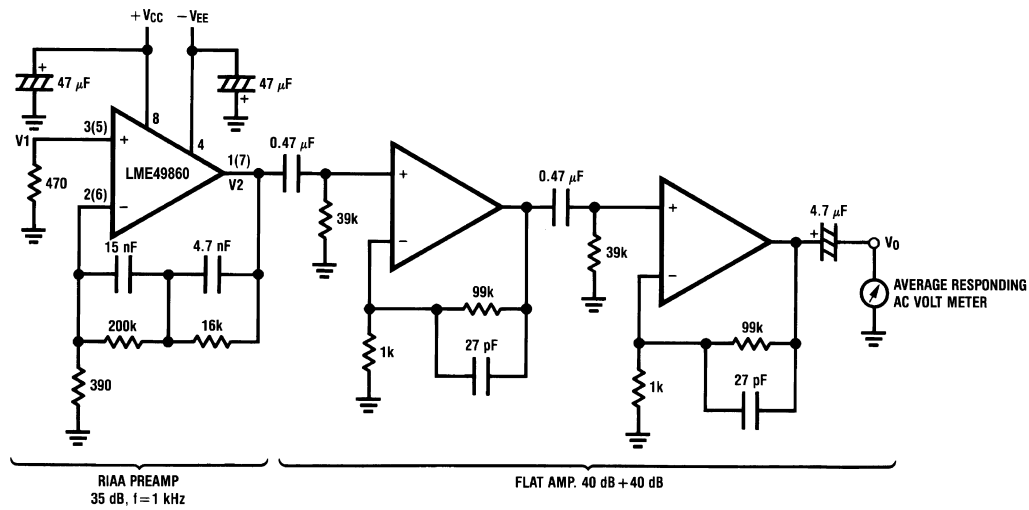


Figure 5. THD+N and IMD Distortion Test Circuit

The LME49860 is a high speed op amp with excellent phase margin and stability. Capacitive loads up to 100pF will cause little change in the phase characteristics of the amplifiers and are therefore allowable.

Capacitive loads greater than 100pF must be isolated from the output. The most straightforward way to do this is to put a resistor in series with the output. This resistor will also prevent excess power dissipation if the output is accidentally shorted.



Complete shielding is required to prevent induced pick up from external sources. Always check with oscilloscope for power line noise.

Figure 6. Noise Measurement Circuit
Total Gain: 115 dB @f = 1 kHz
Input Referred Noise Voltage: $e_n = V_0/560,000$ (V)

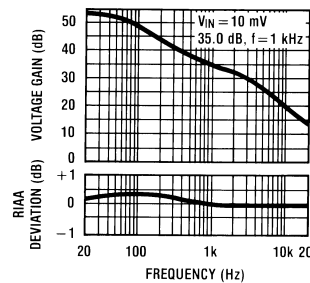


Figure 7. RIAA Preamp Voltage Gain, RIAA Deviation vs Frequency

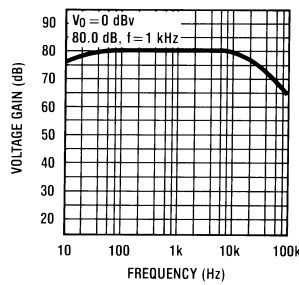
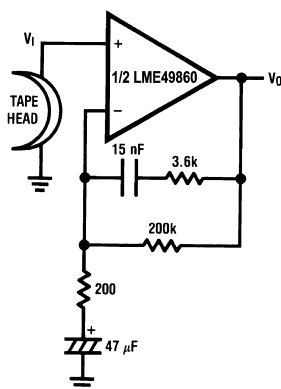


Figure 8. Flat Amp Voltage Gain vs Frequency

TYPICAL APPLICATIONS



$A_V = 34.5$
 $F = 1 \text{ kHz}$
 $E_n = 0.38 \mu\text{V}$
 A Weighted

Figure 9. NAB Preamp

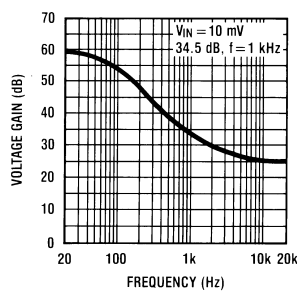
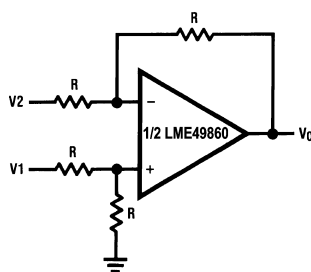
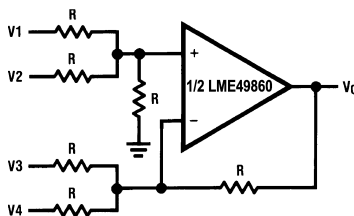


Figure 10. NAB Preamp Voltage Gain vs Frequency



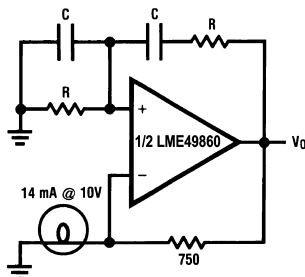
$$V_O = V1 - V2$$

Figure 11. Balanced to Single Ended Converter



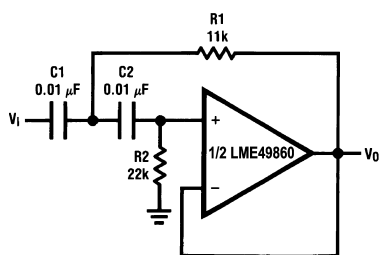
$$V_O = V1 + V2 - V3 - V4$$

Figure 12. Adder/Subtractor



$$f_0 = \frac{1}{2\pi RC}$$

Figure 13. Sine Wave Oscillator



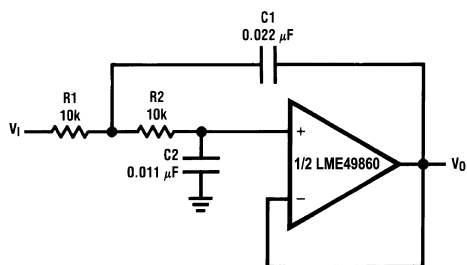
if $C_1 = C_2 = C$

$$R_1 = \frac{\sqrt{2}}{2\omega_0 C}$$

$$R_2 = 2 \cdot R_1$$

Illustration is $f_0 = 1$ kHz

Figure 14. Second Order High Pass Filter (Butterworth)



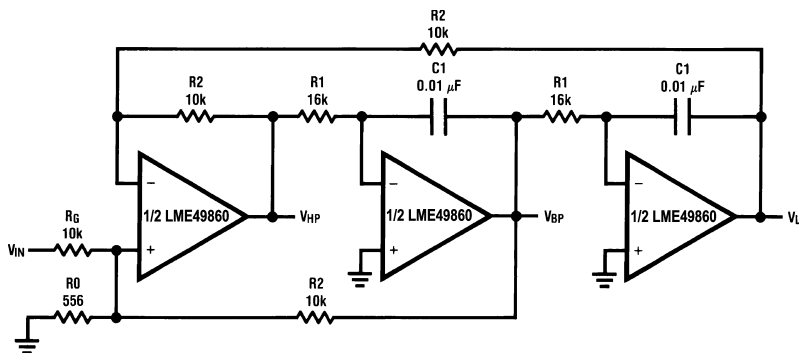
if $R_1 = R_2 = R$

$$C_1 = \frac{\sqrt{2}}{\omega_0 R}$$

$$C_2 = \frac{C_1}{2}$$

Illustration is $f_0 = 1$ kHz

Figure 15. Second Order Low Pass Filter (Butterworth)



$$f_0 = \frac{1}{2\pi C_1 R_1}, Q = \frac{1}{2} \left(1 + \frac{R_2}{R_0} + \frac{R_2}{R_G} \right), A_{BP} = Q A_{LP} = Q A_{LH} = \frac{R_2}{R_G}$$

Illustration is $f_0 = 1$ kHz, $Q = 10$, $A_{BP} = 1$

Figure 16. State Variable Filter

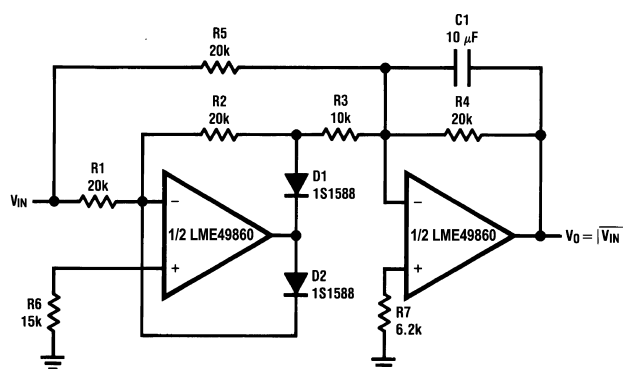


Figure 17. AC/DC Converter

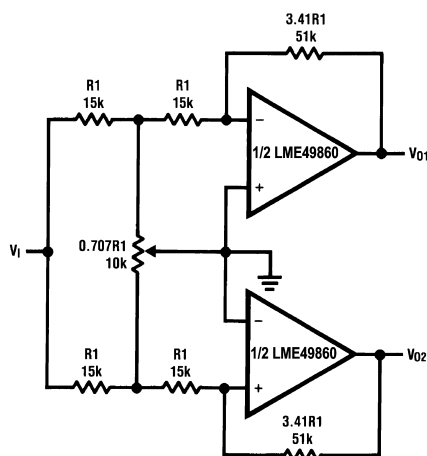


Figure 18. 2 Channel Panning Circuit (Pan Pot)

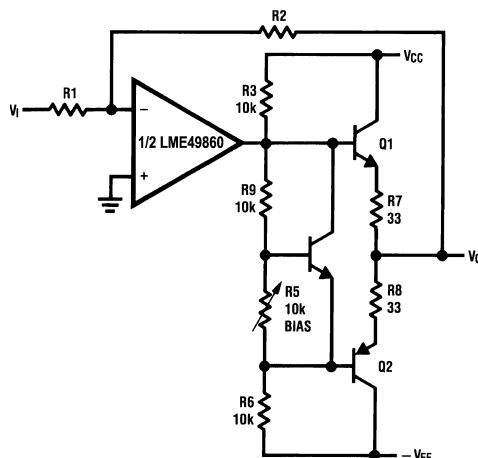
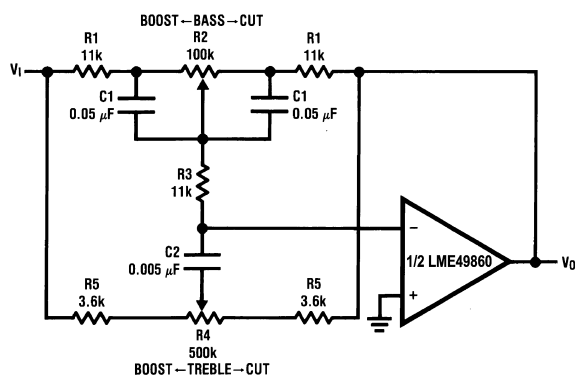


Figure 19. Line Driver



$$f_L = \frac{1}{2\pi R_2 C_1}, f_{LB} = \frac{1}{2\pi R_1 C_1}$$

$$f_H = \frac{1}{2\pi R_5 C_2}, f_{HB} = \frac{1}{2\pi (R_1 + R_5 + 2R_3) C_2}$$

Illustration is:

$$f_L = 32 \text{ Hz}, f_{LB} = 320 \text{ Hz}$$

$$f_H = 11 \text{ kHz}, f_{HB} = 1.1 \text{ kHz}$$

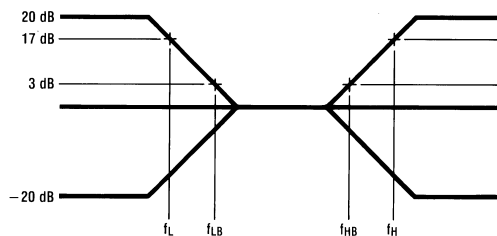
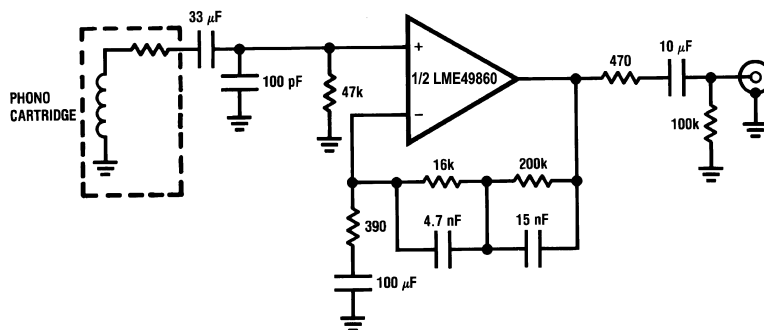
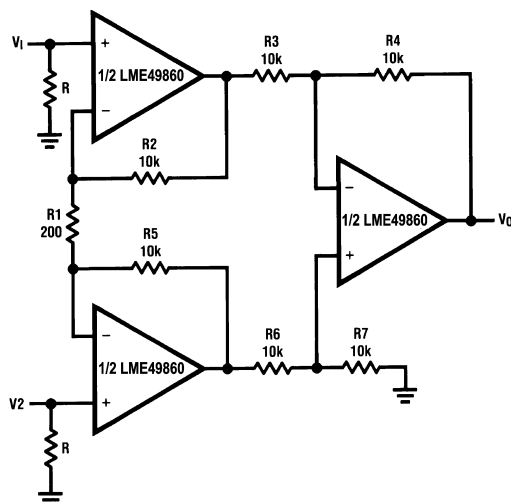


Figure 20. Tone Control



$A_v = 35 \text{ dB}$
 $E_n = 0.33 \mu\text{V}$
 $S/N = 90 \text{ dB}$
 $f = 1 \text{ kHz}$
 $A \text{ Weighted}$
 $A \text{ Weighted, } V_{IN} = 10 \text{ mV}$
 $@f = 1 \text{ kHz}$

Figure 21. RIAA Preamp



If $R_2 = R_5$, $R_3 = R_6$, $R_4 = R_7$

$$V_0 = \left(1 + \frac{2R_2}{R_1}\right) \frac{R_4}{R_3} (V_2 - V_1)$$

Illustration is:

$$V_0 = 101(V_2 - V_1)$$

Figure 22. Balanced Input Mic Amp

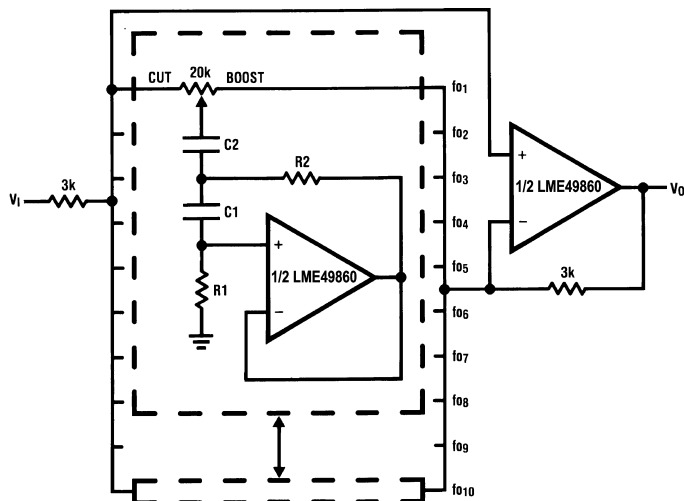


Figure 23. 10 Band Graphic Equalizer

fo (Hz)	C ₁	C ₂	R ₁	R ₂
32	0.12μF	4.7μF	75kΩ	500Ω
64	0.056μF	3.3μF	68kΩ	510Ω
125	0.033μF	1.5μF	62kΩ	510Ω
250	0.015μF	0.82μF	68kΩ	470Ω
500	8200pF	0.39μF	62kΩ	470Ω
1k	3900pF	0.22μF	68kΩ	470Ω
2k	2000pF	0.1μF	68kΩ	470Ω
4k	1100pF	0.056μF	62kΩ	470Ω
8k	510pF	0.022μF	68kΩ	510Ω
16k	330pF	0.012μF	51kΩ	510Ω

Revision History

Rev	Date	Description
1.0	06/01/07	Initial release.
1.1	06/11/07	Added the LME49860MA and LME49860NA Top Mark Information.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LME49860MA/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L49860 MA	Samples
LME49860MAX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	L49860 MA	Samples
LME49860NA/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	Call TI	Level-1-NA-UNLIM	-40 to 85	LME 49860NA	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LME49860MAX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LME49860MAX/NOPB	SOIC	D	8	2500	349.0	337.0	45.0

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.

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